

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	49	(("5879987") or ("5314788") or ("6042929") or ("5489488") or ("5528055") or ("5663084") or ("5830776") or ("5834991") or ("6072550") or ("6083567") or ("6165657") or ("6209481") or ("6209481") or ("4266223") or ("4302744") or ("4380749") or ("4466850") or ("4544941") or ("4551607") or ("4595791") or ("4630025") or ("4631820") or ("4755418") or ("4768863") or ("4793281") or ("4795516") or ("4804816") or ("4805070") or ("4831491") or ("4831493") or ("4853721") or ("4854265") or ("4854974") or ("4857907") or ("4885527") or ("4892592") or ("4961817") or ("4972287") or ("4982696") or ("4985985") or ("4987091") or ("5178738") or ("5214296") or ("5230145") or ("5279989") or ("5281843") or ("5285088") or ("5290725") or ("5341267") or ("5372912")).PN.	USPAT; USOCR	OR	OFF	2005/05/06 15:54
S1	5	((("20040101995") or ("20040106288") or ("20040097086") or ("20040097081") or ("20040106235")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/02 10:58
S2	6	((("20040101995") or ("20040106288") or ("20040097086") or ("20040097081") or ("20040106235") or ("20040092129") or ("20040106235")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/02 11:47
S3	19511	laminat\$4 WITH film\$4 WITH conduct\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 12:04
S4	7163	S3 AND (copper OR Cu)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 12:05

S5	4872	S4 AND circuit\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 12:05
S6	385	S5 AND (etch\$4 WITH chlorid\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 08:11
S7	192	S6 AND semi\$1conduct\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 14:42
S9	167	S7 AND resin\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 12:27
S10	11	("4868584" "4970283" "5108210" "5157107" "5252703" "5449584" "5516875" "5518864" "5578697" "5670609" "5756650").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/02 14:08
S11	1	("6096482").URPN.	USPAT	OR	OFF	2005/05/02 17:14
S12	129	S7 AND electrod\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 14:43
S13	100	S12 AND (electrod\$4 WITH semi\$1conduct\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 08:11
S14	89	S13 AND resin\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 16:24
S15	2	(("6146960") or ("4541893")).PN.	USPAT; USOCR	OR	OFF	2005/05/02 17:07
S16	1	("6,462,274").PN.	USPAT; USOCR	OR	OFF	2005/05/02 17:07

S17	259805	circuit\$4 WITH substrate\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 17:15
S18	139153	S17 AND semi\$1conduct\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 17:16
S19	75235	S18 AND ((metal\$4 OR conduct\$4) WITH (film\$4 OR layer\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 08:09
S20	40390	S19 AND electrode\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 17:18
S21	10156	S20 AND laminat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 17:18
S22	373	S21 AND (etch\$4 WITH chlorid\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 17:23
S23	9	S22 AND (etch\$4 WITH iodi\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 17:19
S24	329	S22 AND resin\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/02 17:23
S25	33159	(circuit\$4 WITH substrate\$4) AND (semi\$1conduct\$4 WITH element\$4)	US-PGPUB; USPAT; JPO	OR	OFF	2005/05/02 18:10

S26	6125	S25 AND (mount\$4 WITH element\$4)	US-PGPUB; USPAT; JPO	OR	OFF	2005/05/02 18:09
S27	33208	(circuit\$4 WITH substrate\$4) AND (semi\$1conduct\$4 WITH element\$4)	US-PGPUB; USPAT; JPO	OR	OFF	2005/05/03 08:09
S28	22350	S27 AND ((metal\$4 OR conduct\$4) WITH (film\$4 OR layer\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 08:10
S29	10765	S28 AND (electrod\$4 WITH semi\$1conduct\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 08:11
S30	266	S29 AND (etch\$4 WITH chlorid\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 11:23
S31	4	("5362926").URPN.	USPAT	OR	OFF	2005/05/03 08:49
S32	8	("4151543" "4376287" "4628598" "5278429" "5362926" "5545589" "5741575" "5949655").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/03 08:53
S33	3	("6100582").URPN.	USPAT	OR	OFF	2005/05/03 08:56
S34	9	("5495665" "5598307" "5737837" "5835306" "5879787" "5978177" "6100582" "6162996" "6198052").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/03 09:00
S35	33208	(circuit\$4 WITH substrate\$4) AND (semi\$1conduct\$4 WITH element\$4)	US-PGPUB; USPAT; JPO	OR	OFF	2005/05/03 11:03
S36	22350	S35 AND ((metal\$4 OR conduct\$4) WITH (film\$4 OR layer\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 11:03
S37	10765	S36 AND (electrod\$4 WITH semi\$1conduct\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 11:03

S38	266	S37 AND (etch\$4 WITH chlorid\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 11:24
S39	52	S38 AND (etch\$4 WITH stop\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 11:24
S40	4	("5656550" "5976912" "6238952" "6294830").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/03 11:35
S41	4	("6562660").URPN.	USPAT	OR	OFF	2005/05/03 11:40
S42	194	S37 AND anchor\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 14:58
S43	33208	(circuit\$4 WITH substrate\$4) AND (semi\$1conduct\$4 WITH element\$4)	US-PGPUB; USPAT; JPO	OR	OFF	2005/05/03 14:58
S44	22350	S43 AND ((metal\$4 OR conduct\$4) WITH (film\$4 OR layer\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 14:58
S45	10765	S44 AND (electrod\$4 WITH semi\$1conduct\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 14:58
S46	194	S45 AND anchor\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 14:58
S47	51	S46 AND (over\$2 WITH etch\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 15:02

S48	536	S45 AND ((photo\$1resist\$4 OR resist\$4) WITH taper\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/03 15:06
S49	4525	((216/95,96,105,106) or (438/745, 754) or (29/846,847) or (148/DIG105)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/05 13:14
S50	33297	(circuit\$4 WITH substrate\$4) AND (semi\$1conduct\$4 WITH element\$4)	US-PGPUB; USPAT; JPO	OR	OFF	2005/05/05 13:14
S51	22418	S50 AND ((metal\$4 OR conduct\$4) WITH (film\$4 OR layer\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/05 13:14
S52	10804	S51 AND (electrod\$4 WITH semi\$1conduct\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/05 13:14
S53	269	S52 AND (etch\$4 WITH chlorid\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/05 13:14
S54	5	S49 AND S53	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/05 13:15